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(21) International Application Number: PCT/US00/13077 (22) International Filing Date: 11 May 2000 (11.05.00) (30) Priority Data: <table border="0"> <tr> <td>60/134,656</td> <td>18 May 1999 (18.05.99)</td> <td>US</td> </tr> <tr> <td>60/136,917</td> <td>1 June 1999 (01.06.99)</td> <td>US</td> </tr> <tr> <td>60/141,344</td> <td>28 June 1999 (28.06.99)</td> <td>US</td> </tr> <tr> <td>60/150,437</td> <td>24 August 1999 (24.08.99)</td> <td>US</td> </tr> <tr> <td>60/150,869</td> <td>26 August 1999 (26.08.99)</td> <td>US</td> </tr> <tr> <td>09/524,148</td> <td>14 March 2000 (14.03.00)</td> <td>US</td> </tr> </table> (71) Applicant (for all designated States except US): AMERASIA INTERNATIONAL TECHNOLOGY, INC. [US/US]; 70 Washington Road, Princeton Junction, NJ 08550 (US). (72) Inventor; and (75) Inventor/Applicant (for US only): CHUNG, Kevin, Kwong-Tai [US/US]; 116 Wilson Road, Princeton, NJ 08540 (US). (74) Agents: BERARD, Clement, A. et al.; Dann, Dorfman, Herrell and Skillman, P.C., 1601 Market Street, Suite 720, Philadelphia, PA 19103-2307 (US).		60/134,656	18 May 1999 (18.05.99)	US	60/136,917	1 June 1999 (01.06.99)	US	60/141,344	28 June 1999 (28.06.99)	US	60/150,437	24 August 1999 (24.08.99)	US	60/150,869	26 August 1999 (26.08.99)	US	09/524,148	14 March 2000 (14.03.00)	US	(81) Designated States: CN, JP, KR, SG, US, European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE). Published <i>With international search report.</i>
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(54) Title: HIGH-DENSITY ELECTRONIC PACKAGE, AND METHOD FOR MAKING SAME																				
(57) Abstract A high density electronic package (100, 100'', 300, 300') includes a low-modulus-of-elasticity flexible adhesive interposer substrate (110, 210, 310, 330, 500) to which an electronic device, (120, 320, 620, 622, 624, 626) such as a semiconductor chip or die or other component, is attached. The flexible adhesive interposer substrate (110, 210, 310, 330, 500) includes a sheet or layer (111, 211, 311, 331, 520, 530) of a molecularly flexible adhesive having via holes therein in which are built up conductive vias (112, 212, 312, 315, 335, 550, 618) to which contacts of the electronic device (120, 320, 620, 622, 624, 626) connect. A thin layer of metal foil (113, 213, 313, 510, 540) on one surface of the flexible adhesive sheet (111, 211, 311, 331, 520, 530) is patterned to provide contacts and to connect electrically to the conductive vias (112, 212, 312, 315, 335, 550, 618). The electronic device (120, 320, 620, 622, 624, 626) may be covered by a lid (130) or by an encapsulant (137) attached to the flexible adhesive interposer substrate (110, 210, 310, 330, 500) and/or the electronic device (120, 320, 620, 622, 624, 626). An electronic package (300) may include a plurality of electronic devices (320-1, 320-2, 320-3) and respective flexible adhesive interposers (310-1, 310-2, 310-3, 330-1, 330-2, 330-3) that are electrically interconnected.																				